



8013-1147

PATENTS

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Hirokazu HONDA

Confirmation No. 7187

Serial No. 09/678,609

Group 2827

Filed October 4, 2000

Examiner D. Graybill

MULTILAYER INTERCONNECTION BOARD,  
SEMICONDUCTOR DEVICE HAVING THE  
SAME, AND METHOD OF FORMING THE  
SAME AS WELL AS METHOD OF MOUNTING  
THE SEMICONDUCTOR CHIP ON THE  
INTERCONNECTION BOARD

RECEIVED  
JAN -5 2004  
TECHNOLOGY CENTER 29

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

ST AVAILABLE COPY

Sir:

In compliance with Rules 1.97 and 1.98, and in fulfillment of the duty of disclosure under Rule 1.56, the accompanying documents, copies of which are attached to this statement, are made of record on the enclosed Form PTO-1449.

A concise explanation of the relevance of these items is that these references were cited by the Japanese Patent Office in an Official Action. A copy of the Japanese Official Action in which they were cited is attached hereto, with what is believed to be the pertinent portion enclosed in a wavy line. An English translation of the enclosed portion is also attached hereto.

Under the provisions of 37 CFR 1.97(e), the undersigned hereby certifies that each item of information contained in this Supplemental Information Disclosure Statement

HONDA S.N. 09/678,609

was first cited in any communication from a foreign Patent Office in a counterpart foreign application not more than three months prior to the filing of this Statement.

Respectfully submitted,

YOUNG & THOMPSON

By



Robert J. Patch  
Attorney for Applicant  
Registration No. 17,355  
745 South 23rd Street  
Arlington, VA 22202  
Telephone: 703/521-2297

December 31, 2003

**BEST AVAILABLE COPY**

[illegible]